



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

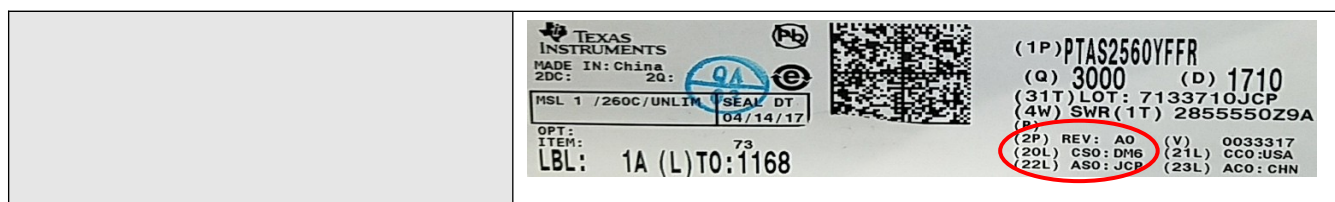
PCN Number:	20260807003.1	PCN Issued	August 07, 2026
Qualification of TI CDAT and TI Clark as an additional Assembly site for select devices		Sample request deadline:	October 06, 2026
		Estimated 1st ship date:	November 05, 2026
Sample requests received after October 06, 2026 will not be supported.			

Change type(s)
Assembly Site
Assembly Process
Assembly Material
Packing/Shipping/Labeling

PCN Details

Description of Change:		
Texas Instruments is pleased to announce the qualification of TI CDAT and TI Clark as an additional Assembly site for select devices. Material differences between sites as follows.		
	Current site	Additional site
Assembly site	CARZ	CDAT/CLARK
Wire bond diam/type	0.8mil Au	0.8mil Cu
Mold compound	SID#441141	4222198
Lead finish	NiPdAuAg	NiPdAu
Qual details are provided in the Qual Data Section.		
Reason for Change:	Continuity of Supply	

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Physical aspects of the device have changed. Request the Supporting Data Packet (SDP) for more details on the changes.			
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			
	RoHS	REACH	Green Status	IEC 62474
	☒ No Change	☒ No Change	☒ No Change	☒ No Change
Changes to product identification resulting from this PCN:	Assembly Site Information			
	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
	CARZ	CSZ	CHN	Jiangsu
	CDAT	CDA	CHN	Chengdu
	CLARK	QAB	PHL	Angeles City
Sample product shipping label (not actual product label):				



Products Affected:		
OPA2990SIRUGR	TLV9102SIRUGR	

Qualification Report

Approve Date 29-July-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLV9102SIRUGR	Qual Device: TLV9102SIRUGR	QBS Package Reference: ADS1115SIRUGR	QBS Product Reference: OPA2990IDR	QBS Package Reference: TLV9034RUCR	QBS Process Reference: PSN7005A1ARSBR	QBS Process Reference: PSN7005A1BRSBR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0	1/77/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0	1/77/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	3/231/0	3/231/0	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	3/231/0	-	2/154/0	1/77/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	1/77/0	-	-
HTOL	B1	Life Test	Tj=125C, Ta=107C	1000 Hours	-	-	-	-	-	2/154/0	1/77/0
ELFR	B2	ELFR	Tj=125C, Ta=107C	48 Hours	-	-	-	-	-	2/2000/0	1/1000/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	3/15/0	3/15/0	1/22/0	1/22/0	-	3/15/0	3/15/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/15/0	-	-	-	-	3/60/0	3/60/0
ESD	E2	ESD CDM	-	250 Volts	3/9/0	3/9/0	-	1/3/0	1/3/0	2/6/0	1/3/0
ESD	E2	ESD CDM	-	1000 Volts	3/9/0	-	-	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	3/9/0	3/9/0	-	1/3/0	-	2/6/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	3/9/0	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	1/3/0	-	2/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	1/30/0	-	1/30/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	1/Pass	-	-	1/Pass	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device TLV9102SIRUGR is qualified at MSL1 260C

Qual Device TLV9102SIRUGR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2606-006

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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